

MB05F~MB10F

Rev.A Apr.-2021

描述 / Descriptions

1A 表面贴装玻璃钝化整流桥，薄型 MBF 封装。

1A Surface Mount Glass Passivated Bridge Rectifier, MBF thin package.

特征 / Features

玻璃钝化芯片，反向电压：50V~1000V，正向电流：1A，浪涌电流大，低正向压降，引线和管体皆符合 RoHS 标准，无卤产品。

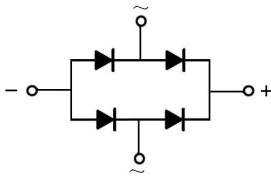
Glass Passivated Chip Junction, Reverse Voltage:50to1000V, Forward Current:1 A, High Surge Current Capability, Low Forward Voltage Drop, Lead and body according with RoHS standard, Halogen free product.

用途 / Applications

一般用途。

General purpose.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

印章代码 / Marking

见印章说明。 See Marking Instructions.

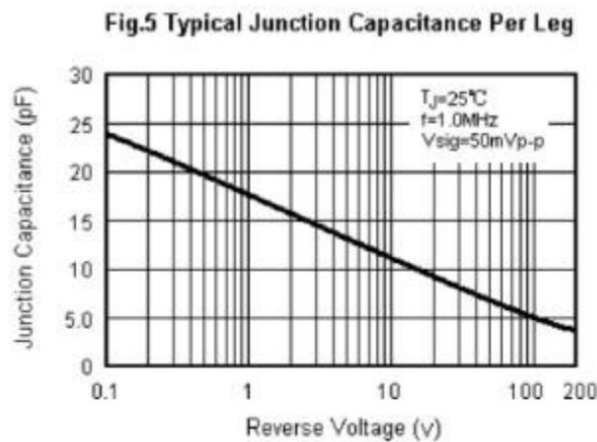
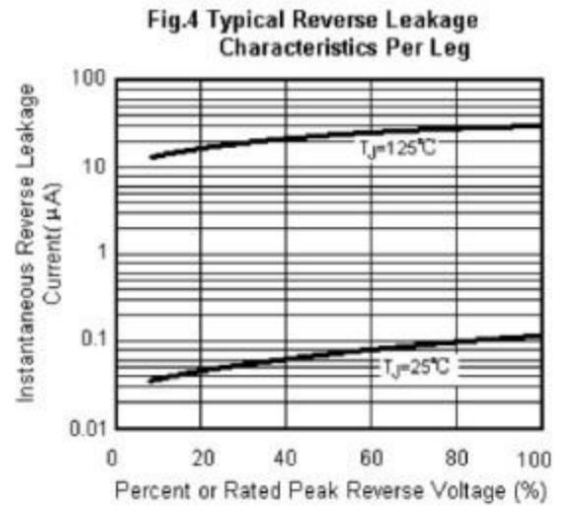
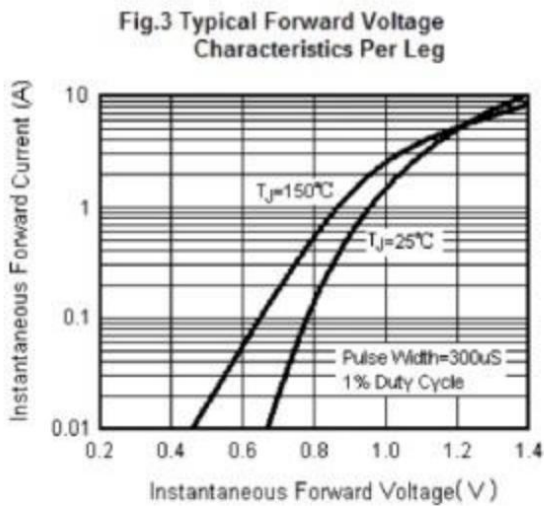
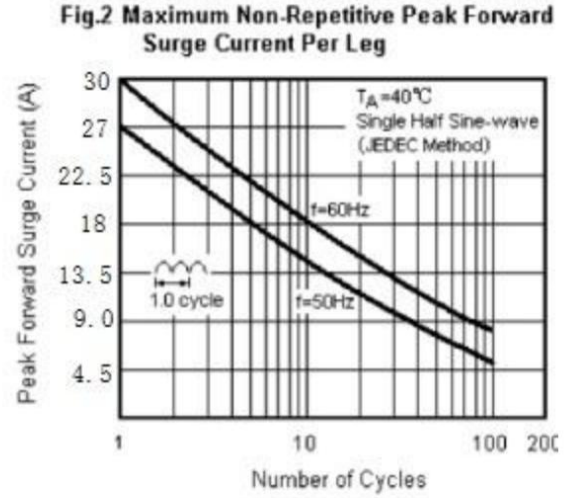
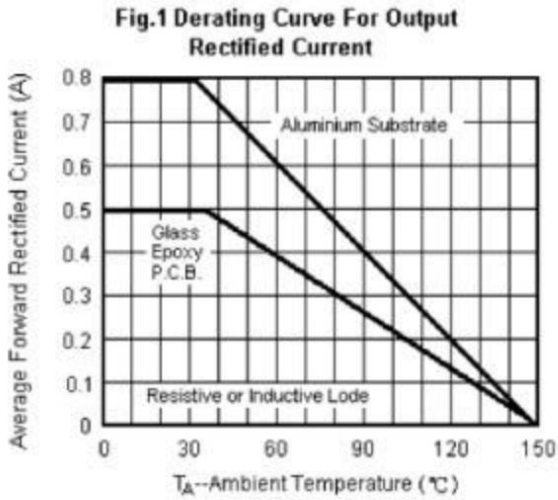
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 40°C	$I_{F(AV)}$	1							A
Peak Forward Surge Current,8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	30							A
I ² t Rating for Fusing(t<8.3ms)	I_t^2	5							A ² s
VR=4.0V,f=1MHZ Typical Junction Capacitance	C_j	13							pF
Typical Thermal Resistance	$R_{\theta JA}$	60							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 to +150							°C

电性能参数 / Electrical Characteristics(Ta=25°C)

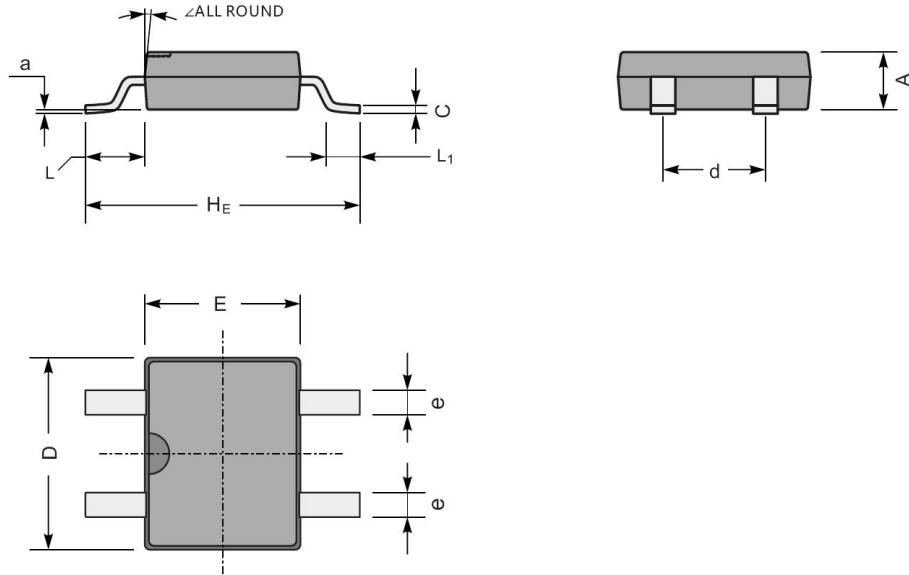
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Max Instantaneous Forward Voltage	V_F	$I_F=0.5A$	1.0	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^\circ C$	5.0	μA
		$T_a=125^\circ C$	500	μA

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

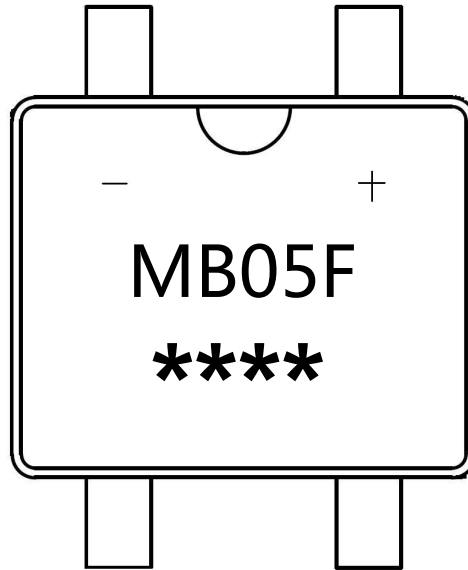
MBF



MBF mechanical data

UNIT		A	C	D	E	H_E	d	e	L	L_1	a	\angle
mm	max	1.6	0.22	5.0	4.1	7.0	2.7	0.8	1.7	1.1	0.2	7°
	min	1.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	—	
mil	max	63	8.7	197	161	276	106	31	67	43	8	
	min	47	5.9	177	142	252	91	20	51	20	—	

印章说明 / Marking Instructions



说明

MB05F : 为型号代码

**** : 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

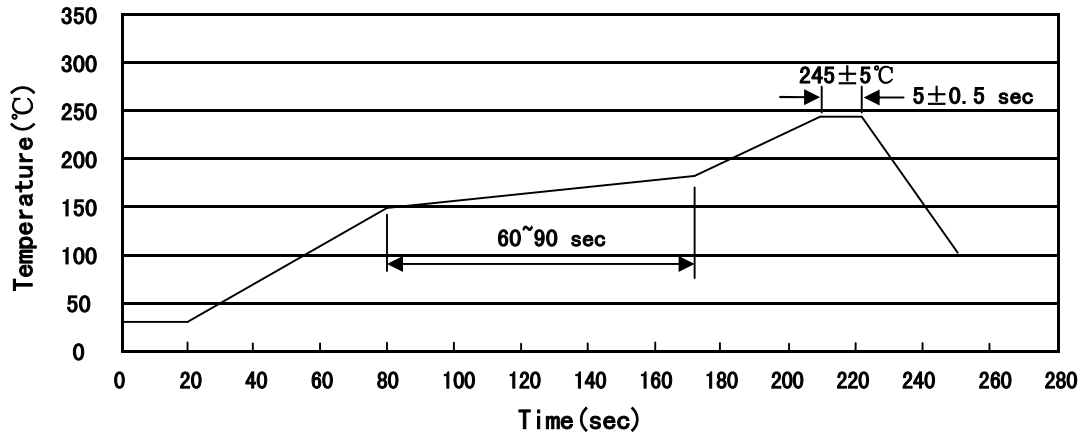
MB05F : Product Type Code

**** : Lot No. Code , The 1st * means:YM Code , The last 3 * means:little Lot No Code

Marking

Type number	Marking code
MB05F	MB05F
MB1F	MB1F
MB2F	MB2F
MB4F	MB4F
MB6F	MB6F
MB8F	MB8F
MB10F	MB10F

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
MBF	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

使用说明 / Notices